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April 21, 2017

Product change

New shockproof packaging for mounting assembly for printed circuit boards

The packing of the EPCOS P-core mounting assembly for printed circuit boards (terminal carriers and yokes) has been improved. Up to now, these assemblies were packed in bulk. In the future they will be plugged into polystyrene or polyethylene foam boards. This will make the packing more resistant against external mechanical shocks and other impacts during transport.

Affected products

Ordering code	Type (Core, mounting assemblies)
B65518D2001*	P9/5
B65518D2002*	P9/5
B65535B0003*	P11/7
B65545B0010*	P14/8
B65545B0009*	P14/8
B65615B0001*	P36/22
B65655B0009*	P18/11
B65655B0010*	P18/11
B65665C0004*	P22/13
B65675B0005*	P26/16
B65705B0003*	P30/19

The ordering codes and packing units remain unchanged.

Planned introduction: July 31, 2017

Enclosure PCN (ID No. MAG-462040417)

Contact Dr. Bernard Michaud, MAG TF F PM, Munich

Customers are asked to address inquiries directly to their sales contacts.



Product / Process Change Notification

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Customer feedback		
Customer acknowledgement	Signature	

Email bernard.michaud@epcos.com